

**Interested to join our international team of  
successful Chip Design and Verification Engineers in our  
Chipglobe Dresden, Munich or Belgrade Design Center?**



## **Test Engineer (m/f/d)**

Chipglobe is focusing on Design– and Verification Consulting with both Insourcing (at Customer premises) and Outsourcing (Chipglobe Design Center) working models. Our teams work in a global setup with ASIC design, verification and software teams in major semiconductor companies, focusing on markets in automotive, telecommunications, security and networking. Chipglobe headquarters is located in Munich/Germany a Chipglobe Design Center in Dresden/Germany, a Chipglobe Design Center in Belgrade/Serbia and in Ho Chi Minh City/Vietnam as well as a Chipglobe Entity in Singapore. We are more than 90 experts with an experienced management team. Based on the strong experience of our staff we manage and execute projects in a well-communicated, success-proven and sustainable way. We love what we do and we do what we love.

### **ChipGlobe Offering:**

- ✓ Opportunity to work for stable, expanding German company with mature management, that is technically involved
- ✓ Excellent working environment, encouraging both technical and personal involvement
- ✓ Work together with a team of 90+ senior experts across multiple expertise domains in a global team setup
- ✓ Strategic partnerships with leading semiconductor companies
- ✓ New and challenging innovative projects
- ✓ Transparent Chipglobe yearly bonus system

### **Job Description:**

- ✓ Test program development on Automatic Test Equipment (ATE)
- ✓ Analyze, debug and characterize new products on the ATE
- ✓ Test package transfer to production sites
- ✓ Member of a test engineering team

### **Job requirements – Technical Skills - for Junior:**

- ✓ Master in Electrical Engineering
- ✓ programming skills in VBA or C++
- ✓ Microsoft Office skills

### **Job requirements – Technical Skills - for Senior:**

- ✓ programming an ATE like Teradyne J750/Flex or Advantest 93k (93000)
- ✓ mixed signal know how
- ✓ test hardware development for wafer and packaged level
- ✓ propose DFT concept and test time ratio
- ✓ 5+ years experience

### **Job requirements – Soft Skills**

- ✓ Communication
  - Able to abstract technical details. Open to communicate with people on and off site.
  - Excellent communication skills, enjoys working in an international team across locations
  - A very good level of spoken and written English (at least B2 level).
  - Strong presentation and listening skills are required
- ✓ Team player - Committed to the team and task. Helping team members, sharing knowledge
- ✓ Self-driven and highly motivated
  - Self motivated, Embracing the task, Highlight potential issues, Regular reporting
  - Clean, structured, organized working style
- ✓ Solution oriented attitude, pragmatic. Good problem solving skills
  - Following and improving processes. Able to follow corporate reporting standards
- ✓ Organized, trusted, committed to a long term employment at Chipglobe
- ✓ Ability to work under pressure and adapt to changing requirements

If you are interested in this position, please send your CV and the reason why you would like to join Chipglobe to:

[employment@chipglobe.com](mailto:employment@chipglobe.com)